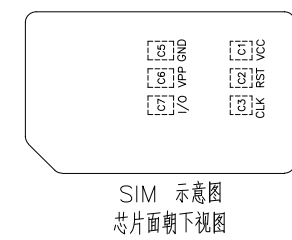
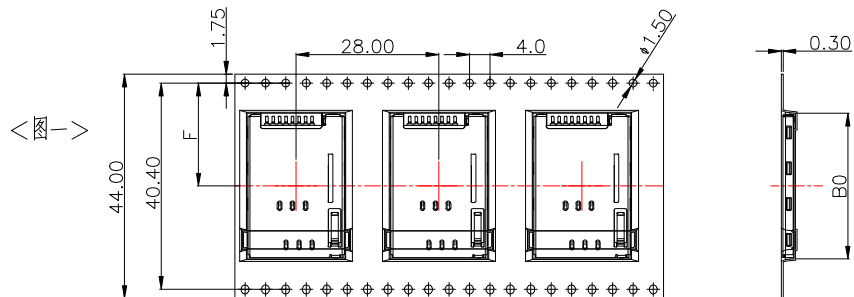


- Specification
- * Electrical Characteristics :
 - Current Rating: 0.5A AC/DC Max.
 - Dielectric Withstanding Voltage: 250V AC/DC
 - Insulation Resistance: 500M ohms Min.
 - Contact Resistance: 100m ohms Max.
 - * Mechanical Characteristics:
 - Mating Cycles: 5000 Insertions.
 - * Environmental :
 - Operating Temperature: -40°C to +85°C.
 - * Material:
 - Housing: HI-Temp plastic UL 94V-0 Rated.
 - Contact: Copper Alloy.
 - Shell: Stainless Steel SUS 304, t=0.20mm.
 - * Plating :
 - Terminal:
 - Contact area: Gold Flash Plated Over 40u" Nickel.
 - Solder area: 80u" Tin Plated Over 40u" Nickel.
 - Under plate: 40u"Min. Nickel.
 - Shell:
 - 30u"Min. Nickel Plated Over All,
 - Solder Area: Gold Flash.

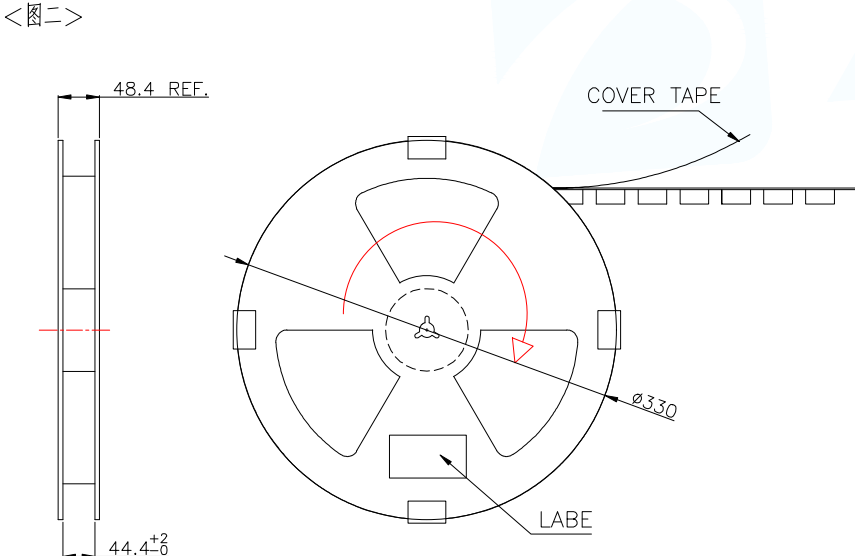
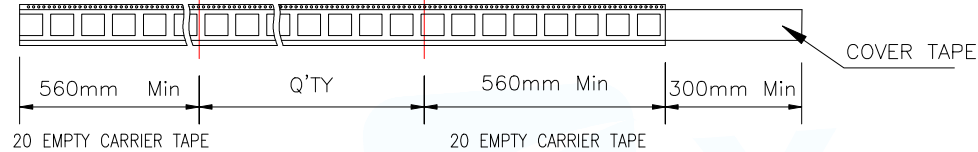


PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	CD SW LOWER
P8#	CD SW UPPER

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: SIM PUSH H2.2客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-135-ARP8
DECIMALS:	ANGLES:	DWN		
.X:±0.30	X':±2'	CHKD		
.XX:±0.20	X.X':±1'	APVD		
.XXX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	



包装收料 ← 客户拉出方向 →

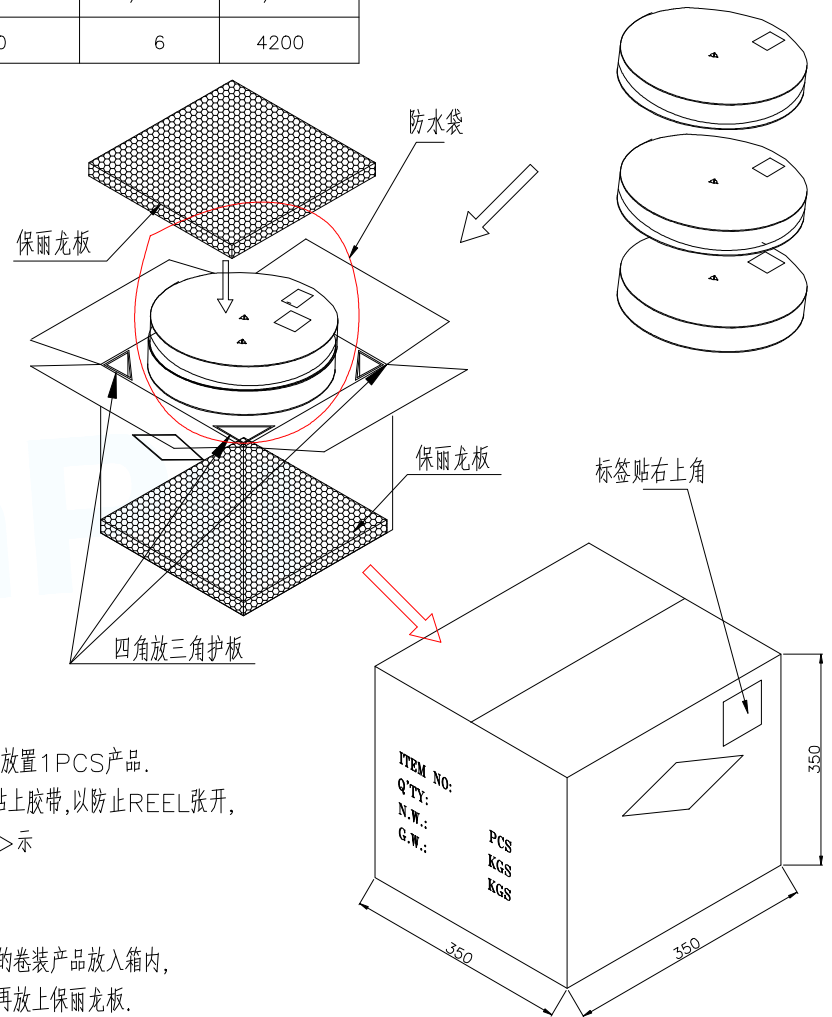


- NOTE:
- 依<图一>示放置产品于下载中,每穴放置1PCS产品.
 - 包装机包好后,在REEL的个等分点贴上胶带,以防止REEL张开,每REEL贴1PCS标签,如<图二>示
 - 包装数量见如<TABLE 1>示
 - 包装成箱见如<图三>示
箱底放保丽龙板,再依次将指定数量的卷装产品放入箱内,四角分别放入四个三角护板,最上层再放上保丽龙板.
 - 封箱,在封好的纸箱上按客户要求写上料号,数量等

<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
700	6	4200

<图三>



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: SIM PUSH H2.2客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-135-ARP8
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.XX:±0.20	X.X':±1"	APVD		
.XXX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	

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